



60V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} max	I _D max T _A = 25°C
	8mΩ @ V _{GS} = 10V	14.0A
60V	$12m\Omega @ V_{GS} = 4.5V$	11.5A

Description and Applications

This new generation N-Channel Enhancement Mode MOSFET is designed to minimize R_{DS(ON)}, yet maintain superior switching performance. This device is ideal for use in notebook battery power management and loadswitch.

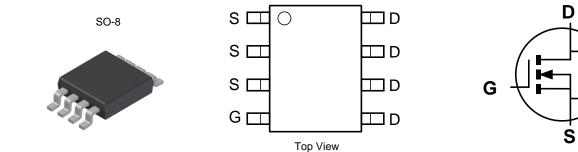
- Backlighting
- **Power Management Functions**
- **DC-DC** Converters

Features and Benefits

- 100% Unclamped Inductive Switch (UIS) Test in Production
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On-State Losses
- Low Input Capacitance •
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.074 grams (Approximate)



Internal Schematic



Ordering Information (Note 4)

Top View

Part Number	Case	Packaging
DMT6010LSS-13	SO-8	2,500/Tape & Reel

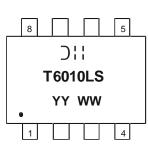
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



⊃¦¦ = Manufacturer's Marking T6010LS = Product Type Marking Code YYWW = Date Code Marking YY or \overline{YY} = Year (ex: 13 = 2013) WW = Week (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	60	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 6) V _{GS} = 10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	14.0 11.0	А
	t<10s	T _A = +25°C T _A = +70°C	ID	16.7 13.5	А
Maximum Continuous Body Diode Forward Current (Note 6)			I _S	3	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	80	A
Avalanche Current, L = 0.1mH			I _{AS}	20	A
Avalanche Energy, L = 0.1mH			E _{AS}	20	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)		PD	1.5	W
Thermal Basistones, lunction to Ambient (Note 5)	Steady State	D	80	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	R _{θJA}	48	°C/W
Total Power Dissipation (Note 6)		PD	2.0	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	P	53	°C/W
memai Resistance, Junction to Ambient (Note 6)	t<10s	R _{θJA}	37	°C/W
Thermal Resistance, Junction to Case (Note 6)		R _{eJC}	6.5	°C/W
Operating and Storage Temperature Range		TJ, T _{STG}	-55 to +150	°C

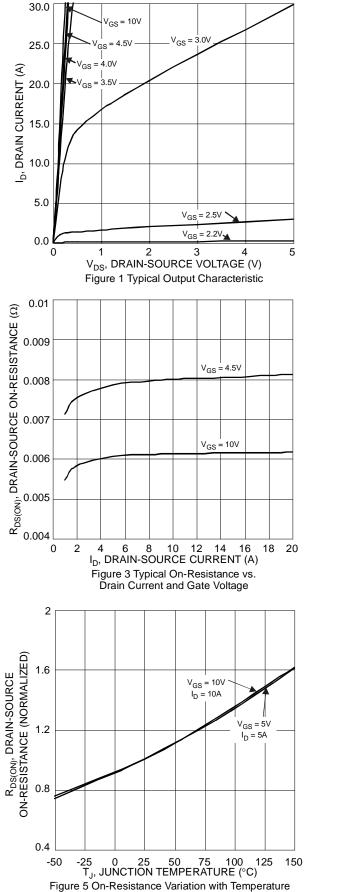
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	60		_	V	$V_{GS} = 0V, I_{D} = 250 \mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μA	$V_{DS} = 48V, V_{GS} = 0V$	
Gate-Source Leakage	IGSS			±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)						•	
Gate Threshold Voltage	V _{GS(TH)}	0.8	—	2.0	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	
Static Drain-Source On-Resistance			6	8	mΩ	$V_{GS} = 10V, I_D = 20A$	
Static Drain-Source On-Resistance	R _{DS(ON)}		8	12	11152	$V_{GS} = 4.5V, I_D = 20A$	
Diode Forward Voltage	V _{SD}		0.9	1.2	V	$V_{GS} = 0V, I_{S} = 20A$	
DYNAMIC CHARACTERISTICS (Note 8)	DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss		2,090	—		$V_{DS} = 30V, V_{GS} = 0V,$ f = 1MHz	
Output Capacitance	Coss		746	-	pF		
Reverse Transfer Capacitance	C _{rss}		38.5	—			
Gate resistance	R _G		0.59	-	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg		19.3	—		V _{DS} = 30V, I _D = 20A	
Total Gate Charge (V _{GS} = 10V)	Qg		41.3	-	nC		
Gate-Source Charge	Q _{gs}		6.0	-	ne		
Gate-Drain Charge	Q _{gd}	_	8.8	—			
Turn-On Delay Time	t _{D(ON)}	_	5.7	—		V _{DD} = 30V, V _{GS} = 10V,	
Turn-On Rise Time	t _R		4.3	_	ns		
Turn-Off Delay Time	t _{D(OFF)}		23.4	_	115	$I_D = 20A, R_G = 3\Omega$	
Turn-Off Fall Time	t _F	_	9.7	_			

 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:

7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.





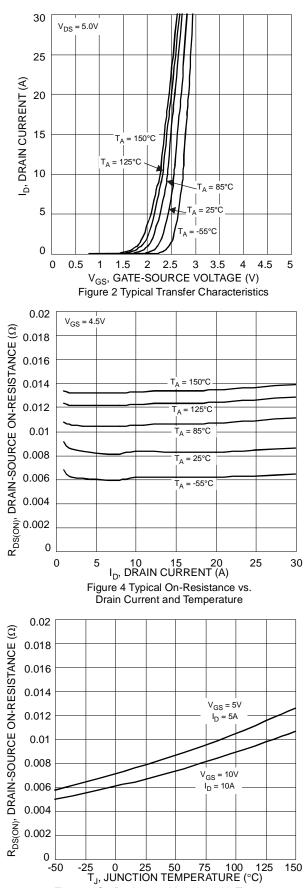
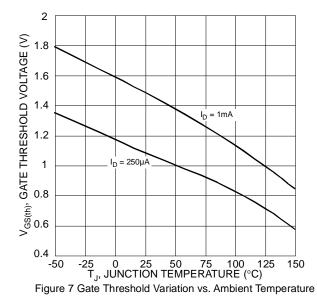
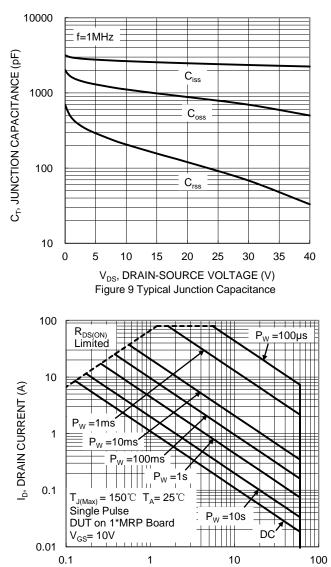


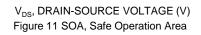
Figure 6 On-Resistance Variation with Temperature

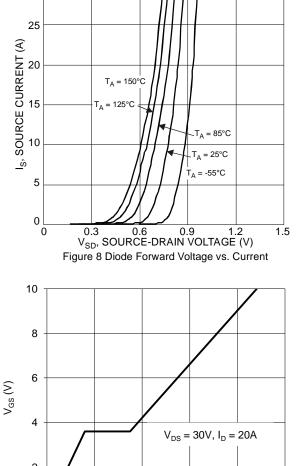












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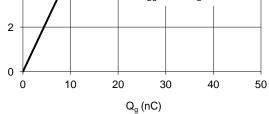
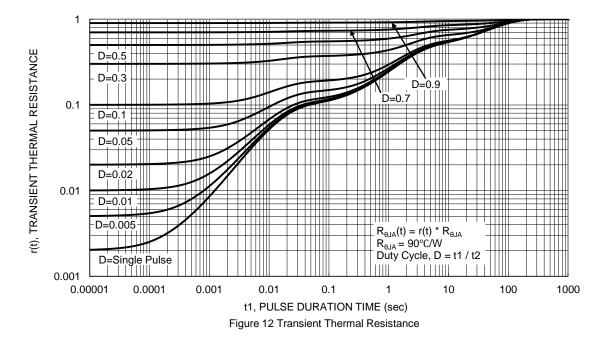


Figure 10 Gate Charge





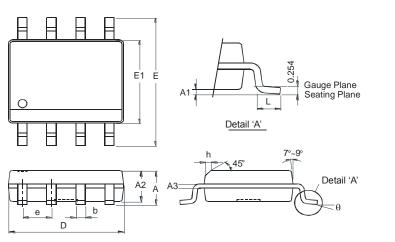






Package Outline Dimensions

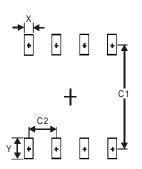
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version



	SO-8		
Dim	Min	Max	
Α	_	1.75	
A1	0.10 0.20		
A2	1.30	1.50	
A3	0.15	0.25	
b	0.3	0.5	
D	4.85	4.95	
Е	5.90	6.10	
E1	1 3.85 3.95		
е	1.27 Тур		
h		0.35	
L	0.62	0.82	
θ	0°	8°	
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



SO-8

Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27

SO-8



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